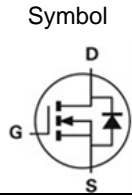
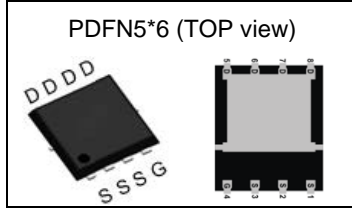


N-Channel Enhancement Mode MOSFET

Pin Description



Ordering Information

Symbol	N-Channel	Unit
V _{DSS}	100	V
R _{DS(ON)-Max}	6	mΩ
I _D	86	A

Feature

- Fast switching speed
- Reliable and Rugged
- ROHS Compliant & Halogen-Free
- 100% UIS and Rg Tested

Applications

- Portable Equipment
- Battery Powered System

Ordering Information

Orderable Part Number	Package Type	Form	Shipping	Marking
SR1A060NAK8A	PDFN5*6	Tape & Reel	5000 / Tape & Reel	1A060 □□□□□□

Absolute Maximum Ratings (T_J=25°C Unless Otherwise Noted)

Symbol	Parameter		N-Channel	Unit
V _{DSS}	Drain-Source Voltage		100	V
V _{GSS}	Gate-Source Voltage		±20	
T _J	Maximum Junction Temperature		150	°C
T _{STG}	Storage Temperature Range		-55 to 150	°C
I _{DM} ①	Pulse Drain Current Tested	T _C =25°C	142	A
I _D	Continuous Drain Current	T _C =25°C	86	A
		T _C =100°C	55	
P _D	Maximum Power Dissipation	T _C =25°C	89	W
		T _C =100°C	36	
I _{AS} ②	Avalanche Current, Single pulse	L=0.1mH	18	A
E _{AS} ②	Avalanche Energy, Single pulse	L=0.1mH	16	mJ

Thermal Characteristics

Symbol	Parameter		Rating	Unit
R _{θJC}	Thermal Resistance-Junction to Case	Steady State	1.4	°C/W
R _{θJA} ③	Thermal Resistance-Junction to Ambient	Steady State	50	°C/W

Note ① : Max. current is limited by bonding wire

Note ② : UIS tested and pulse width are limited by maximum junction temperature 150°C

Note ③ : Surface Mounted on 1in² FR-4 board with 1oz.

N-Channel Electrical Characteristics (T_J=25°C Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
Static Electrical Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _{DS} =250uA	100	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	V _{DS} =80V, V _{GS} =0V	-	-	1	uA
V_{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _{DS} =250uA	1	2	3	V
I_{GSS}	Gate Leakage Current	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA
R_{DS(ON)} ^④	Drain-Source On-state Resistance	V _{GS} =10V, I _{DS} =20A	-	4.6	6	mΩ
		V _{GS} =4.5V, I _{DS} =10A	-	6.6	8.6	
g_{fs}	Forward Transconductance	V _{DS} =5V, I _{DS} =20A	-	3.1	-	S
Dynamic Characteristics [®]						
R_G	Gate Resistance	V _{GS} =0V, V _{DS} =0V, Freq.=1MHz	-	1.7	-	Ω
C_{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =50V, Freq.=1MHz	-	3005	-	pF
C_{oss}	Output Capacitance		-	541	-	
C_{rss}	Reverse Transfer Capacitance		-	20	-	
t_{d(ON)}	Turn-on Delay Time	V _{GS} =10V, V _{DS} =50V, I _D =1A, R _{GEN} =3Ω	-	11	-	nS
t_r	Turn-on Rise Time		-	20	-	
t_{d(OFF)}	Turn-off Delay Time		-	42	-	
t_f	Turn-off Fall Time		-	25	-	
Q_g	Total Gate Charge	V _{GS} =4.5V, V _{DS} =50V I _D =20A	-	32.4	-	nC
Q_g	Total Gate Charge	V _{GS} =10V, V _{DS} =50V, I _D =20A	-	59	-	
Q_{gs}	Gate-Source Charge		-	8.1	-	
Q_{gd}	Gate-Drain Charge		-	16.4	-	
Source-Drain Characteristics						
V_{SD} ^④	Diode Forward Voltage	I _{SD} =20A, V _{GS} =0V	-	0.85	1.1	V
t_{rr}	Reverse Recovery Time	I _F =20A, V _R =50V	-	55.6	-	nS
Q_{rr}	Reverse Recovery Charge	dI _F /dt=100A/μs	-	109.2	-	nC

Note ④ : Pulse test (pulse width≤300us, duty cycle≤2%).

Note ⑤ : Guaranteed by design, not subject to production testing.

Leadpower-semi

N-Channel Typical Characteristics

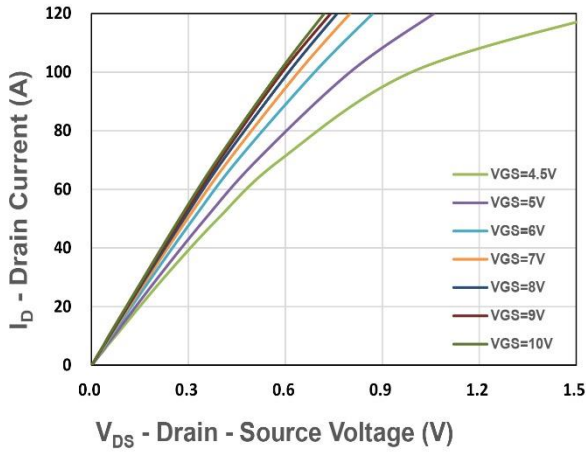


Figure 1. Output Characteristics

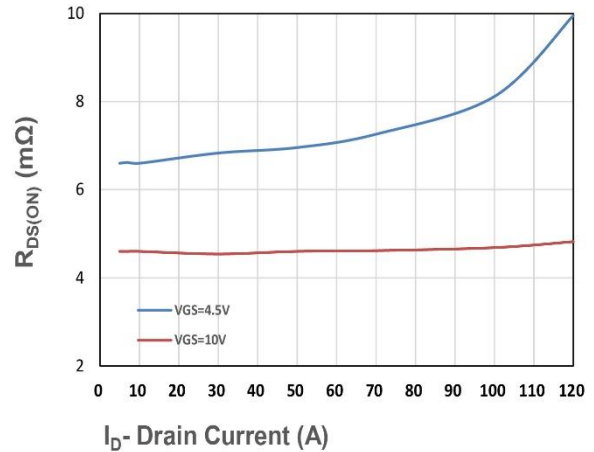


Figure 2. On-Resistance vs. ID

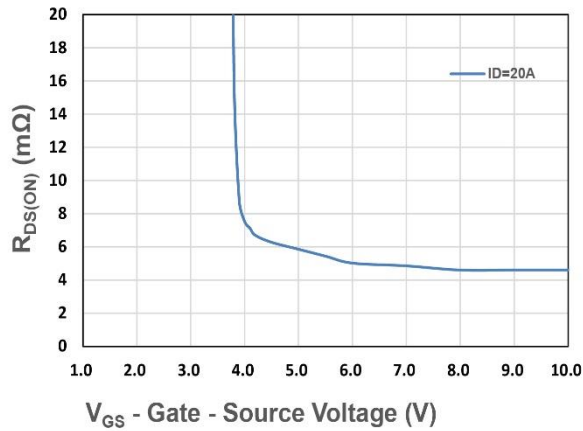


Figure 3. On-Resistance vs. VGS

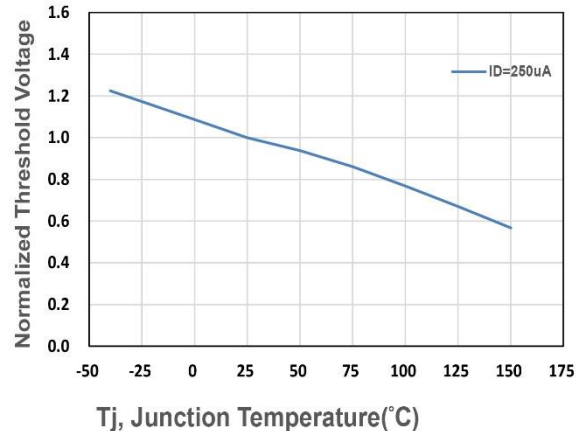


Figure 4. Gate Threshold Voltage

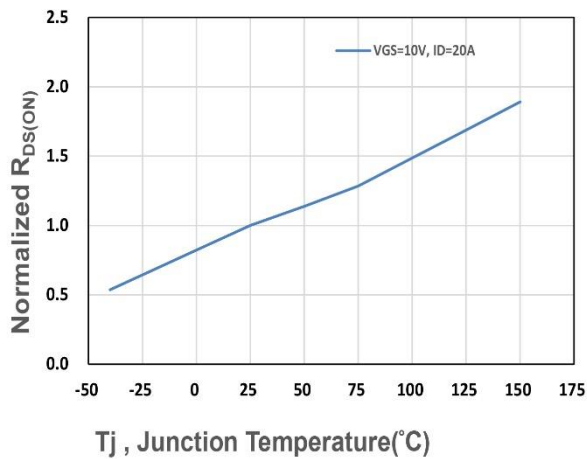


Figure 5. Drain-Source On Resistance

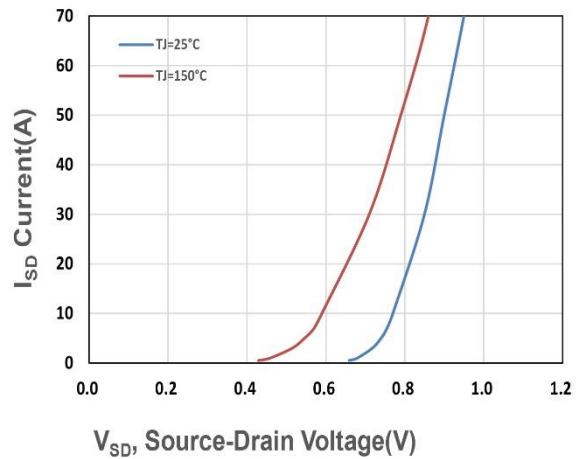
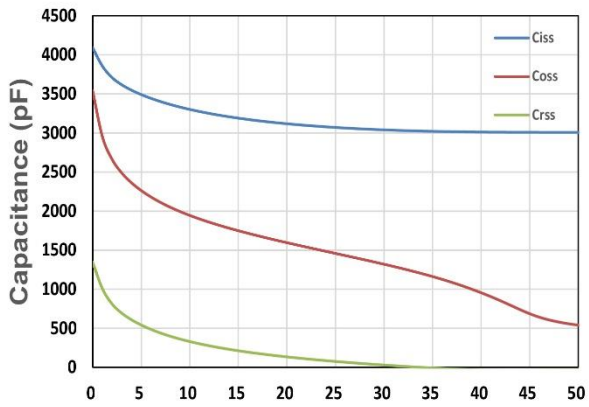
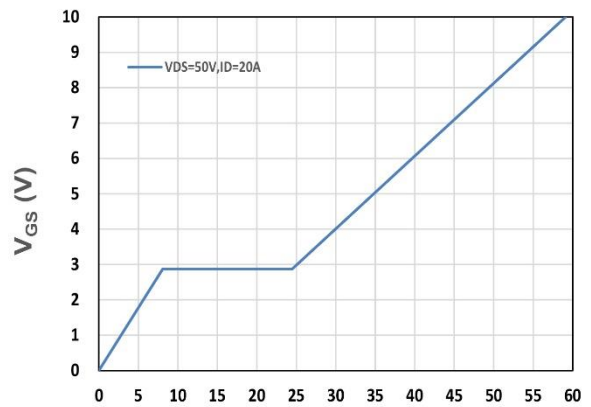


Figure 6. Source-Drain Diode Forward



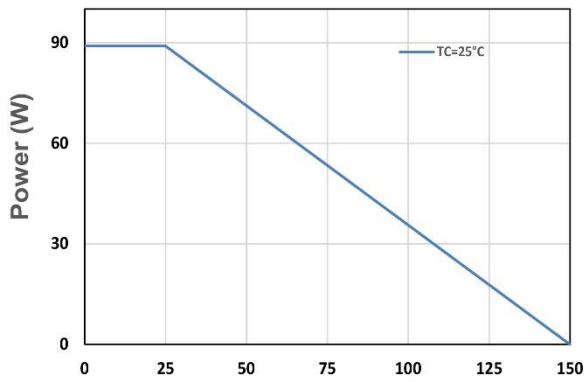
V_{DS} - Drain - Source Voltage (V)

Figure 7. Capacitance



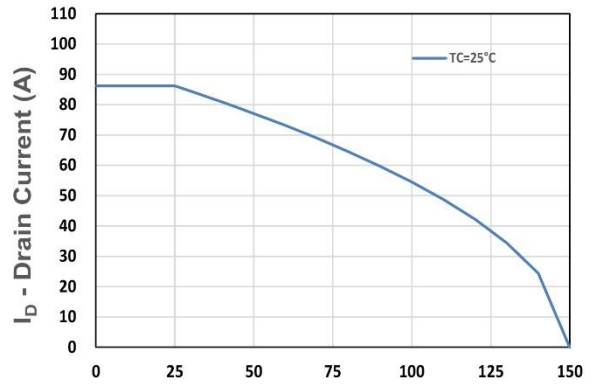
Q_g , Total Gate Charge (nC)

Figure 8. Gate Charge Characteristics



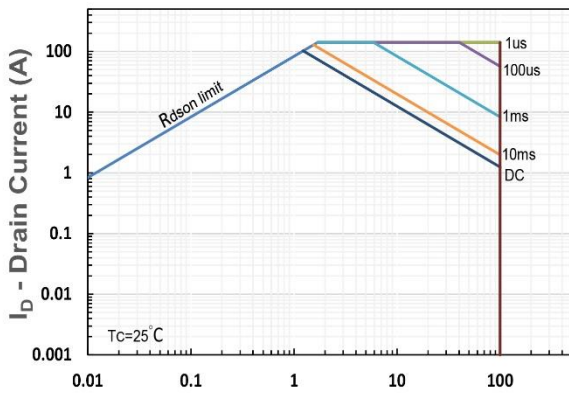
T_j - Junction Temperature ($^{\circ}C$)

Figure 9. Power Dissipation



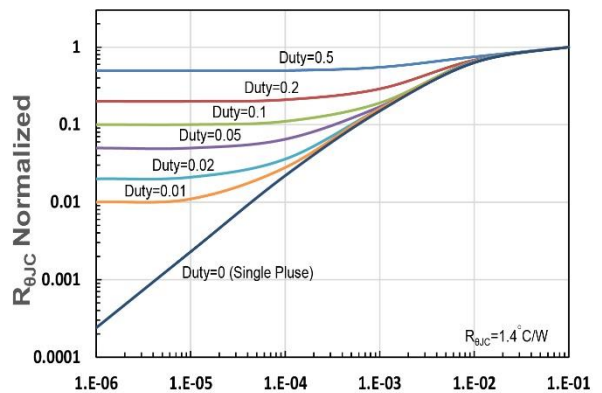
T_j - Junction Temperature ($^{\circ}C$)

Figure 10. Drain Current



V_{DS} - Drain-Source Voltage (V)

Figure 11. Safe Operating Area



t_1 , Square Wave Pulse Duration (s)

Figure 12. $R_{\theta JC}$ Transient Thermal Impedance